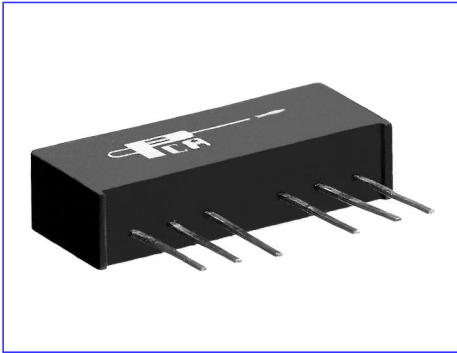


High Speed LAN Interface Module

EPF8076



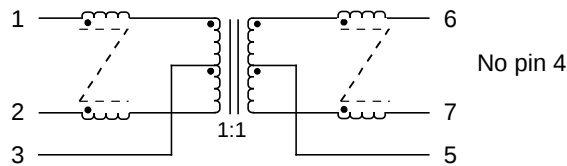
- Optimized for ML6673 •
- Recommended for 10/100, 100 BX, 155 Mb/s applications •
(requiring 1:1 magnetics)
- Guaranteed to operate with 8 mA DC bias at 70°C •
- Complies with or exceeds IEEE 802.3, 10 BT/100 BX Standards •

Electrical Parameters @ 25° C

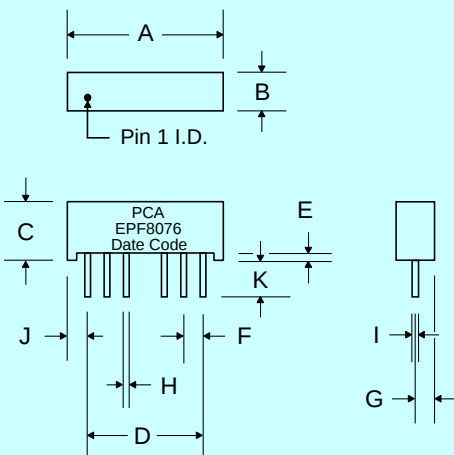
OCL @ 70°C	Insertion Loss (dB Max.)			Return Loss (dB Min.)			Common Mode Rejection (dB Min.)		
100 KHz, 0.1 Vrms 8 mA DC Bias	1-80 MHz	80-100 MHz	100-150 MHz	1-32 MHz	32-62 MHz	62-100 MHz	50 MHz	100 MHz	200 MHz
Cable Side	Xmit	Xmit	Xmit	Xmit	Xmit	Xmit	Xmit	Xmit	Xmit
350μH	-1	-1	-3	-20	-17	-12	-50	-45	-40

• Isolation : 1500 Vrms • Impedance : 100 W • Rise Time : 3.0 nS Max. •

Schematic



Package



Dimensions

Dim.	(Inches)			(Millimeters)		
	Min.	Max.	Nom.	Min.	Max.	Nom.
A	.790	.810		20.07	20.57	
B	.180	.200		4.57	5.08	
C	.300	.320		7.62	8.13	
D	.700	Typ.		17.78	Typ.	
E	.020	.030		.508	.762	
F	.090	Typ.		2.54	Typ.	
G			.090			2.29
H	.016	.022		.406	.559	
I	.008	.012		.203	.305	
J	.065	Typ.		1.65	Typ.	
K	.125	.145		3.18	3.68	



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For best results, the PCB designer should design the outgoing traces preferably to be 50 W, balanced and well coupled to achieve minimum radiation from these traces.